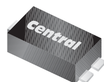
Material Composition Specification

SOT-923 Case



Device average mass . . . . 0.45 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.67%	0.07	Si	7440-21-3	6.67%	0.03	66,667
bond wire	gold	0.67%	0.003	Au	7440-57-5	0.67%	0.003	6,667
leadframe	copper w/ silver plating	47.78%	0.215	Cu	7440-50-8	46.67%	0.21	466,667
				Ag	7440-22-4	1.11%	0.005	11,111
encapsulation*	EMC	42.67%	0.192	silica	7631-86-9	30.67%	0.138	306,667
				epoxy resin	Proprietary	10.67%	0.048	106,667
				Sb_2O_3	1309-64-4	0.89%	0.004	8,889
				TBBA	79-94-7	0.22%	0.001	2,222
				carbon black	1333-86-4	0.22%	0.001	2,222
	EMC GREEN	42.67%	0.192	silica	60676-86-0	28.22%	0.127	282,222
				epoxy resin	37382079-9	4.89%	0.022	48,889
				phenol resin	9003-35-4	4.89%	0.022	48,889
				carbon black	1333-86-4	0.22%	0.001	2,222
				metal hydroxide	1309-42-8	4.44%	0.02	44,444
plating	matte tin	2.22%	0.01	Sn	7440-31-5	2.22%	0.01	22,222

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.